

Product / Package Information

Package	LFCSP - Sawn
Body Size (mm)	3.5 X 3.5 X 0.75 (2.2 EP)
Lead Count	24
Terminal Finish	100 Sn

Environmental Information

RoHS Compliant	Yes
High Temperature Compliant	Yes
Halogen Free Compliant	Yes
REACH SVHC Compliant	Yes

Materials Declaration

Molding Compound

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level		
				Percentage (%)	PPM	Percentage (%)	PPM	
Other inorganic materials	Silica	60676-86-0	1.68E-02	86.2	862000	37.06		370576
Thermosets	Epoxy resin	Proprietary	1.17E-03	6.0	60000	2.58		25794
Thermosets	Phenol resin	Proprietary	1.17E-03	6.0	60000	2.58		25794
Other inorganic materials	Metal Hydroxide	Proprietary	2.92E-04	1.5	15000	0.64		6449
Other inorganic materials	Carbon black	1333-86-4	5.84E-05	0.3	3000	0.13		1290
Subtotal			1.95 E-02	100.00	1000000	42.99		429902

Leadframe

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level		
				Percentage (%)	PPM	Percentage (%)	PPM	
Copper & its alloys	Copper	7440-50-8	1.42 E-02	97.50	975000	31.39		313920
Copper & its alloys	Iron	7439-89-6	3.42 E-04	2.35	23500	0.76		7566
Copper & its alloys	Zinc	7440-66-6	1.75 E-05	0.12	1200	0.04		386
Copper & its alloys	Phosphorus	7723-14-0	4.37 E-06	0.03	300	0.01		97
Subtotal			1.46 E-02	100.00	1000000	32.20		321969

Internal Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level		
				Percentage (%)	PPM	Percentage (%)	PPM	
Precious metals	Silver	7440-22-4	1.46 E-05	100.0	1000000	0.03		322

External Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level		
				Percentage (%)	PPM	Percentage (%)	PPM	
Tin & its alloys	Tin	7440-31-5	8.58 E-04	100.0	1000000	1.89		18944

Bond Wires

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level		
				Percentage (%)	PPM	Percentage (%)	PPM	
Precious metals	Gold	7440-57-5	1.82 E-04	100.0	1000000	0.40		4019

Chip

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level		
				Percentage (%)	PPM	Percentage (%)	PPM	
Other inorganic materials	Doped Silicon	7440-21-3	7.54 E-03	100.0	1000000	16.65		166463

Die Attach

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level		
				Percentage (%)	PPM	Percentage (%)	PPM	
Precious metals	Silver	7440-22-4	2.05 E-03	77.71	777100	4.54		45368
Thermoset	Epichlorohydrin-formaldehyde-phenol copolymer	9003-36-5	8.22 E-05	3.11	31100	0.18		1816
Other organic materials	Epoxy resin, epichlorohydrin-dimer fatty acid	68475-94-5	8.22 E-05	3.11	31100	0.18		1816
Other organic materials	Butyrolactone, gamma-	96-48-0	8.22 E-05	3.11	31100	0.18		1816
Other organic materials	Poly(oxypropylene)diamine	9046-10-0	8.22 E-05	3.11	31100	0.18		1816
Other organic materials	2,6-Diglycidyl phenyl allyl ether oligomer	Unassigned	8.22 E-05	3.11	31100	0.18		1816
Other organic materials	Organosilane	TS ref# 10001	8.22 E-05	3.11	31100	0.18		1816
Other inorganic materials	Copper(II) oxide	1317-38-0	8.22 E-05	3.11	31100	0.18		1816
Other organic materials	Epoxy resin modifier	TS ref# 10038	1.37 E-05	0.52	5200	0.03		304
Subtotal			2.64 E-03	100.0	1000000	5.84		58381

Package Totals			Weight (g) 4.53 E-02			Percentage (%) 100		PPM 1000000
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Note: The information provided in this declaration are true to the best of ADI's knowledge. ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability to any inaccuracy of such information.



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